

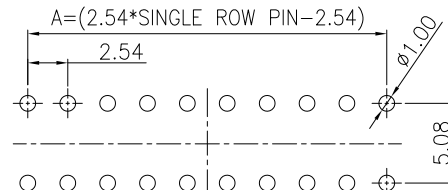
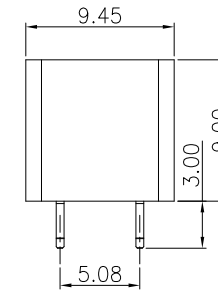
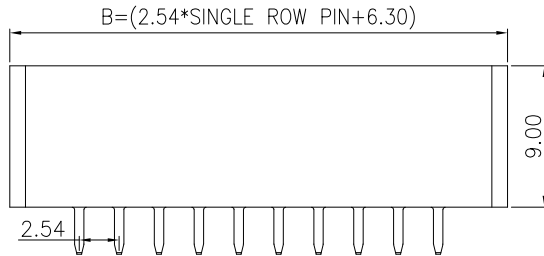
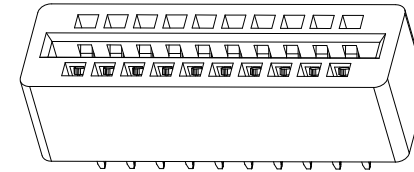
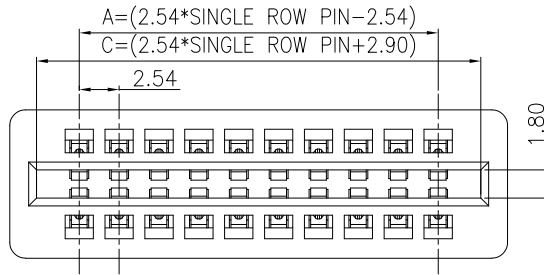
客户图

NOTES:

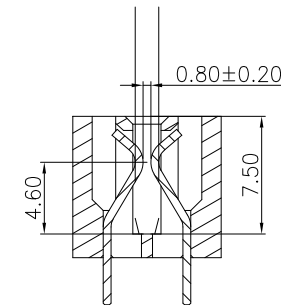
1. MATERIAL:
- 1.1 HOUSING: PA9T BLACK,UL94V-0.
 - 1.2 CONTACT: Copper Alloy,GOLD (SEE P/N) PLATED IN CONTACT AREA, 80u" MIN MATTE TIN PLATED IN SOLDER AREA,50u" MIN. NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
- 2.1 CURRENT RATING:3A;
 - 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 750V AC/MINUTE.
 - 2.3 CONTACT RESISTANCE: 20mΩ MAX.
 - 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
 - 2.5 OPERATION TEMPERATURE:-55°C TO +125°C.
3. ORDER INFORMATION:

61H3- XXX SX 090 C 01

Pin数码 SEE TABLE	端子电镀: S0=Gold Flash/Tin	塑胶高度: 090=9.00mm	包装方式: C=TRAY
004=2X02PIN	S1=1u" Gold/Tin		
008=2*04PIN	S2=3u" Gold/Tin		
.....	S3=5u" Gold/Tin		
100=2X50PIN	S4=10u" Gold/Tin		



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05



					OPERATION	DRAW	WLY	2020.09.17	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
					X.X ±0.40	DESIGN	Jensen	2020.09.17					
					X.XX ±0.25	CHECK	Jack	2020.09.17					
					X.XXX ±0.15	APPROVE	Andy	2020.09.17					
A0		NEW			Angle ±3'				SHEET	1/1	TITLE:	2.54 SOLT 180°DIP W9.45*H9	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-2057	

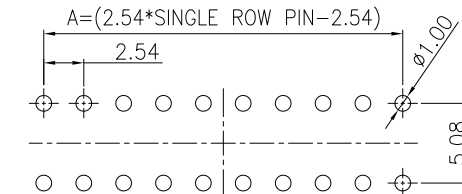
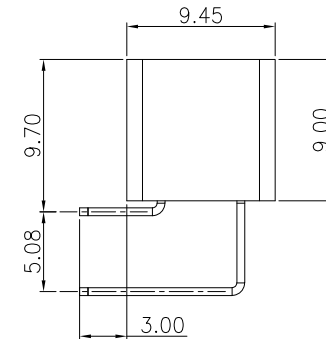
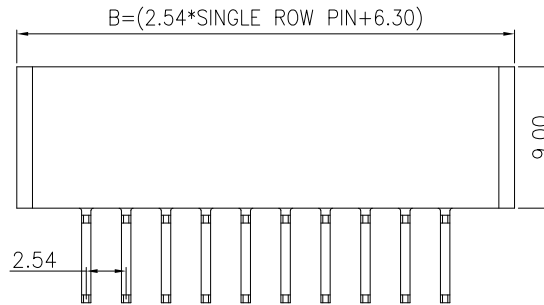
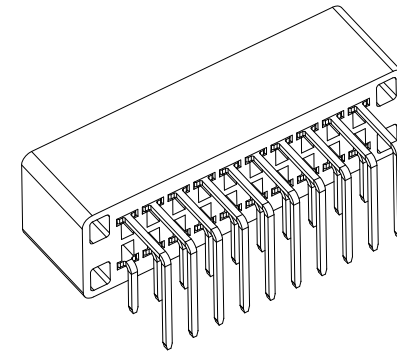
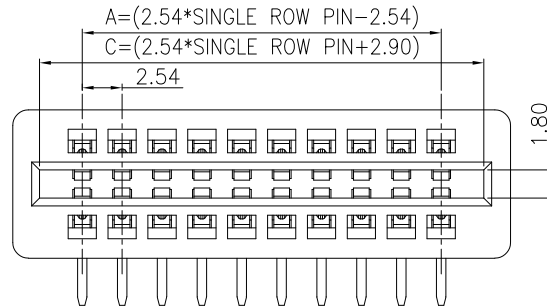
客户图

NOTES:

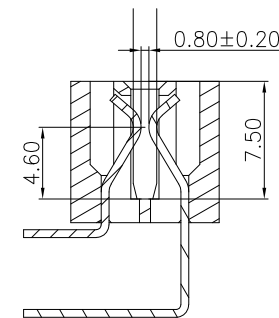
1. MATERIAL:
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 - 1.2 CONTACT: Copper Alloy,GOLD (SEE P/N) PLATED IN CONTACT AREA, 80u" MIN MATTE TIN PLATED IN SOLDER AREA,50u" MIN. NICKEL UNDERPLATED OVERALL.
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 - 2.3 CONTACT RESISTANCE: 20mΩ MAX.
 - 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
 - 2.5 OPERATION TEMPERATURE:-55°C TO +125°C.
3. ORDER INFORMATION:

61H3R- XXX SX 090 C 01

Pin数码 SEE TABLE	端子电镀: S0=Gold Flash/Tin	塑胶高度: 090=9.00mm	包装方式: C=TRAY
004=2X02PIN	S1=1u" Gold/Tin		
008=2*04PIN	S2=3u" Gold/Tin		
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PCB BOARD TOLFRANCF±0.05



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					X.X ±0.40	DESIGN	Jensen	2020.09.17					
					X.XX ±0.25	CHECK	Jack	2020.09.17					
					X.XXX ±0.15	APPROVE	Andy	2020.09.17					
A0		NEW			Angle ±3'				SHEET	1/1	TITLE:	2.54 SOLT 90°DIP W9.45*H9	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-2058	

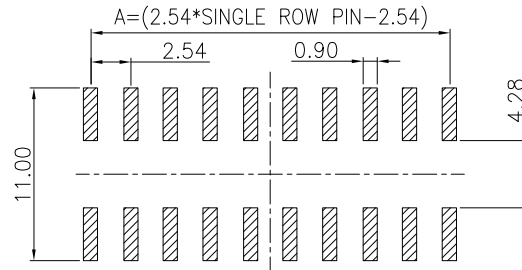
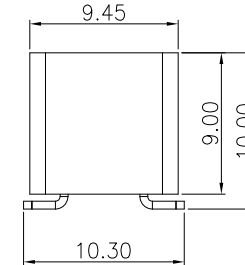
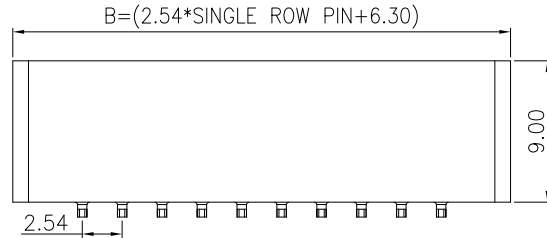
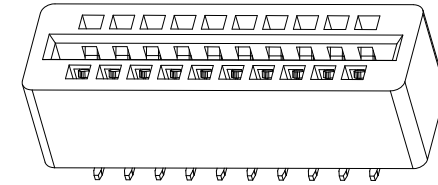
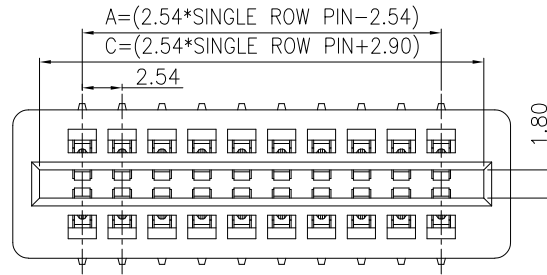
客户图

NOTES:

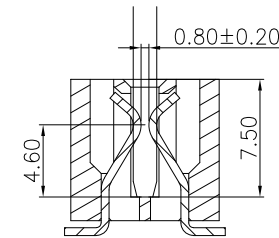
1. MATERIAL:
 - 1.1 HOUSING: PA9T BLACK,UL94V-0.
 - 1.2 CONTACT: Copper Alloy,GOLD (SEE P/N) PLATED IN CONTACT AREA, 80u" MIN MATTE TIN PLATED IN SOLDER AREA,50u" MIN. NICKEL UNDERPLATED OVERALL.
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 - 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 750V AC/MINUTE.
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 - 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
 - 2.5 OPERATION TEMPERATURE:-55°C TO +125°C.
3. ORDER INFORMATION:

61H3M- XXX SX 090 C 01

Pin数码 SEE TABLE	端子电镀: S0=Gold Flash/Tin	塑胶高度: 090=9.00mm	包装方式: C=TRAY
004=2X02PIN	S1=1u" Gold/Tin		
008=2*04PIN	S2=3u" Gold/Tin		
.....	S3=5u" Gold/Tin		
100=2X50PIN	S4=10u" Gold/Tin		



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05



					OPERATION	DRAW	WLY	2020.09.17	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
					X.X ±0.40	DESIGN	Jensen	2020.09.17					
					X.XX ±0.25	CHECK	Jack	2020.09.17					
					X.XXX ±0.15	APPROVE	Andy	2020.09.17					
A0		NEW			Angle ±3°				SHEET	1/1	TITLE:	2.54 SOLT 180°SMT W9.45*H9	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	⊕	DRAW NO.	SP-2056